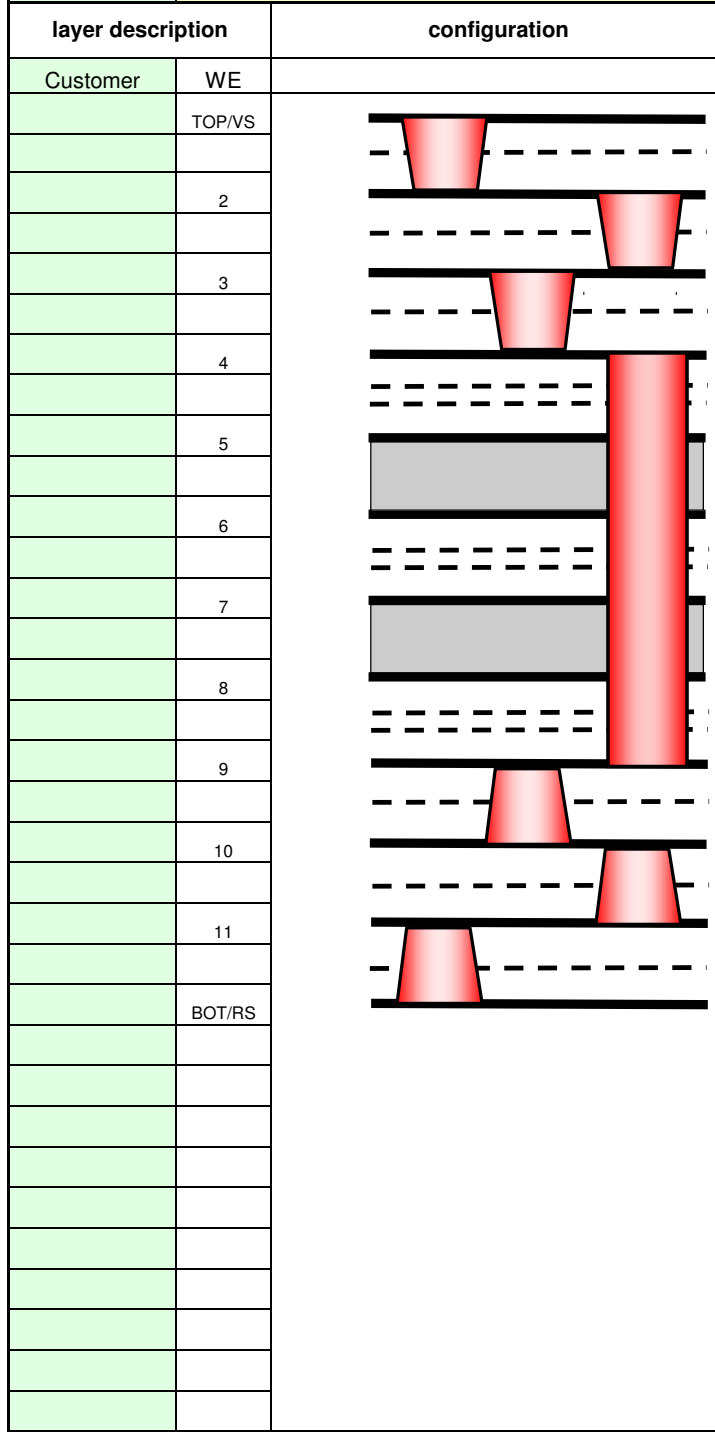


Build Up HDI (Standard)	
HDI12_3+6b+3_1,50_35_engl	12 - Layers Core: 0,51 mm Cu 35/35 µm
WE-Articel No.:	3 + 6B + 3
Customer:	



Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
			[µm]	[µm]
Foil	12 µm	1)	12	
		1 x 1080	60	
Foil	12 µm		30	
		1 x 1080	60	
Foil	12 µm		30	
		1 x 1080	60	
Foil	12 µm		35	
		2 x 1080	133	
	35 µm		33	
0,200 mm			200	
	35 µm		33	
		2 x 1080	124	
	35 µm		33	
0,200 mm			200	
	35 µm		33	
		2 x 1080	133	
Foil	12 µm		35	
		1 x 1080	60	
Foil	12 µm		30	
		1 x 1080	60	
Foil	12 µm		30	
		1 x 1080	60	
Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1496
Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	1,50	+/-	0,13	mm	Date:	Engineer:
thickness with electro plated Cu:	1,59	+/-	0,16	mm		
total thickness with soldermask	1,65	+/-	0,18	mm		
customer requirement		+/-		mm	point:	

prepared: on 29.03.2006 by S. Keller	checked: on 04.05.2006 by M.Kress	approved: on 04.05.2006 by R.Schönholz	revision 00	page: 20-
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